



PC Board Layout

SPECIFICATIONS

- Contact material: 0.35mm phosphor bronze
- Contact plating: Gold on contact area; tin on solder tails
- Housing material: DSM Stanyl TE250F6 (Nylon46)
Heat deflection temperature 290°C, UL94V-0
- Shield material: 0.25mm copper alloy
- Shield plating: Tin

Note: Cavity conforms to FCC rules and regulations Part 68, Subpart F

RoHS compliant

Series	Positions	Contacts	Style	Color	Plating	Options
CTJ	X	XX	D2	BK	PX	XX
Modular jack, single position	8=8 positions 10=10 positions	06=6 contacts 08=8 contacts 10=10 contacts	D2=Style D2	BK=Black	P1=15µ" gold P2=30µ" gold P3=50µ" gold	[blank]=None FS=Full shield

Rev.	Description	Date	Approved	Drawing	Name	Date
				Approved	Howard	01/11/01
				Checked	Lizzy	01/11/01
				Drawn	Tina	01/11/01
				0.0 ± 0.35	0.00 ± 0.20	Angles ± 3'
				UNIT: mm		

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Part No.: **CTJ-8-08-D2-BK-PX-FS2**

Description: Modular jack, 8 position, flat pin, shielded, top entry, PCB mount